ESD Protection Diode

Dual Line CAN Bus Protector

The SZ/NUP2125 has been designed to protect the CAN transceiver from ESD and other harmful transient voltage events. This device provides bidirectional protection for each data line with a single compact SC-70 (SOT-323) package, giving the system designer a low cost option for improving system reliability and meeting stringent EMI requirements.

Features

- 200 W Peak Power Dissipation per Line (8/20 µs Waveform)
- Diode Capacitance Matching
- Low Reverse Leakage Current (< 100 nA)
- IEC Compatibility: IEC 61000-4-2 (ESD): Level 4
 - IEC 61000–4–4 (EFT): 50 A 5/50 ns
 - IEC 61000-4-5 (Lighting) 3.0 A (8/20 μs)
- ISO 7637–1, Nonrepetitive EMI Surge Pulse 2, 8.0 A (1/50 μs)
- ISO 7637–3, Repetitive Electrical Fast Transient (EFT) EMI Surge Pulses, 50 A (5/50 ns)
- Flammability Rating UL 94 V-0
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Devices

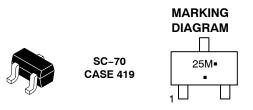
Applications

- Automotive Networks
 - CAN / CAN-FD
 - Low and High-Speed CAN
 - Fault Tolerant CAN



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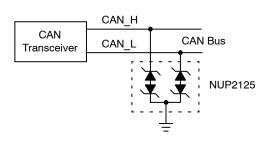
25 = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)





ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

MAXIMUM RATINGS ($T_J = 25^{\circ}C$, unless otherwise specified)

Symbol	Rating	Value	Unit
PPK	Peak Power Dissipation, 8 x 20 μs Double Exponential Waveform (Note 1)	200	W
T _J	Operating Junction Temperature Range	-55 to 150	°C
TJ	Storage Temperature Range	-55 to 150	°C
T _L	Lead Solder Temperature (10 s)	260	°C
ESD	Human Body Model (HBM) Machine Model (MM) IEC 61000–4–2 Contact IEC 61000–4–2 Air ISO 10605 150 pF / 2 k Ω Contact ISO 10605 330 pF / 2 k Ω Contact	8.0 1.6 30 30 30 30	kV kV kV kV kV

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ELECTRICAL CHARACTERISTICS (T_J = 25°C, unless otherwise specified)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
V _{RWM}	Reverse Working Voltage	(Note 2)	24	-	-	V
V _{BR}	Breakdown Voltage	I _T = 1 mA (Note 3)	27	28.5	32	V
I _R	Reverse Leakage Current	V _{RWM} = 24 V	-	15	100	nA
V _C	Clamping Voltage	I _{PP} = 1 A (8/20 μs Waveform) (Note 4)	-	33.4	36.6	V
V _C	Clamping Voltage	I _{PP} = 3 A (8/20 μs Waveform) (Note 4)	-	44	50	V
I _{PP}	Maximum Peak Pulse Current	8/20 μs Waveform (Note 4)	-	-	3.0	Α
CJ	Capacitance	V _R = 0 V, f = 1 MHz (Line to GND)	-	7.0	10	pF
		V _R = 5 V, f = 1 MHz (Line to GND)	-	4.5	6.0	pF
		$V_R = 5 \text{ V, f} = 1 \text{ MHz}$ (Line to GND), $T_A = +150^{\circ}\text{C}$	-	5.0	-	pF
ΔC	Diode Capacitance Matching	V _R = 0 V, 5 MHz (Note 5)	-	0.26	2	%

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Device	Package	Shipping [†]	
NUP2125WTT1G		3000 / Tape & Reel	
SZNUP2125WTT1G*	SC-70		
NUP2125WTT3G	(Pb-Free)	10000 / Tana % Dool	
SZNUP2125WTT3G*		10000 / Tape & Reel	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{1.} Non-repetitive current pulse per Figure 1.

Surge protection devices are normally selected according to the working peak reverse voltage (V_{RWM}), which should be equal or greater than the DC or continuous peak operating voltage level.

^{3.} V_{BR} is measured at pulse test current I_T.

^{4.} Pulse waveform per Figure 1.

ΔC is the percentage difference between C_J of lines 1 and 2 measured according to the test conditions given in the electrical characteristics table.

^{*}SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

TYPICAL PERFORMANCE CURVES

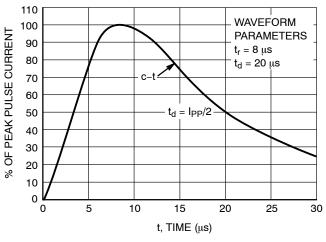
 $(T_J = 25^{\circ}C \text{ unless otherwise noted})$

€

3.5

3.0

2.5

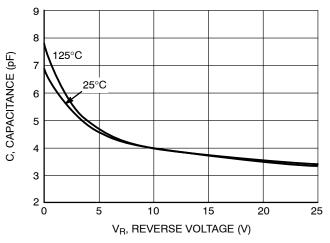


IPP, PEAK PULSE CURRENT 2.0 1.5 1.0 0.5 0.0 35 30 40 45

Figure 1. Pulse Waveform, 8 \times 20 μ s

V_C, CLAMPING VOLTAGE (V) Figure 2. Clamping Voltage vs Peak Pulse Current

50



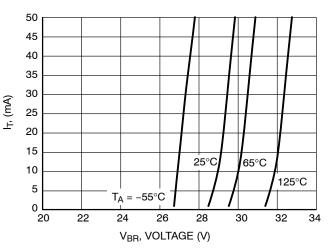
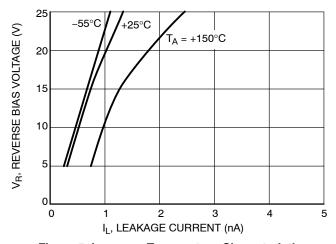


Figure 3. Typical Junction Capacitance vs **Reverse Voltage**

Figure 4. V_{BR} versus I_T Characteristics



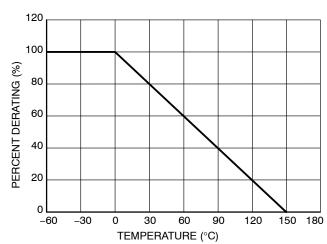


Figure 5. I_R versus Temperature Characteristics

Figure 6. Temperature Power Dissipation Derating

Surge Protection Diode Circuit

Surge protection diodes provide protection to a transceiver by clamping a surge voltage to a safe level. Surge protection diodes have high impedance below and low impedance above their breakdown voltage. A surge protection Zener diode has its junction optimized to absorb the high peak energy of a transient event, while a standard Zener diode is designed and specified to clamp a steady state voltage.

Figure 7 provides an example of a dual bidirectional surge protection diode array that can be used for protection with the high-speed CAN network. The bidirectional array is created from four identical Zener TVS diodes. The clamping voltage of the composite device is equal to the

breakdown voltage of the diode that is reversed biased, plus the diode drop of the second diode that is forwarded biased.

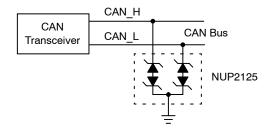
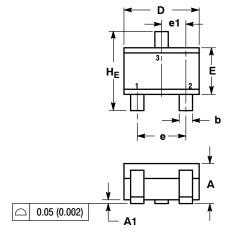


Figure 7. High-Speed and Fault Tolerant CAN Surge Protection Circuit

PACKAGE DIMENSIONS

SC-70 (SOT-323) CASE 419-04



ISSUE N

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.

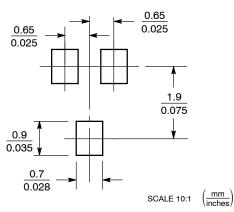
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70 REF 0		0.028 REF			
b	0.30	0.35	0.40	0.012	0.014	0.016
С	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
е	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC		0.026 BSC			
Ĺ	0.20	0.38	0.56	0.008	0.015	0.022
HE	2.00	2.10	2.40	0.079	0.083	0.095

STYLE 11:

PIN 1. CATHODE

2. CATHODE 3. CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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